

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
20V	24mΩ@4.5V	6.5A
	30mΩ@2.5V	
	40mΩ@1.8V	

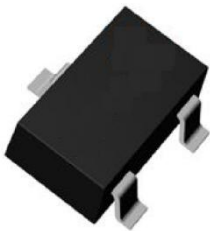
### Feature

- Advanced trench process technology
- High density cell design for low on-resistance
- High power and current handling capability
- Suffix“-Q1”for AEC-Q101

### Application

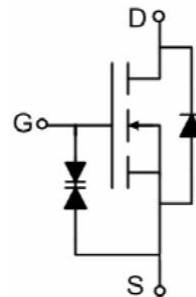
- Load Switch
- PWM Application

### Package

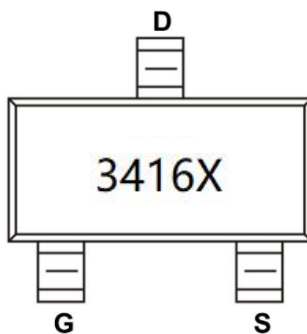


SOT-23

### Circuit diagram



### Marking



### Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	6.5	A
Pulsed Drain Current	$I_{DM}$	30	A
Power Dissipation	$P_D$	1.4	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	89	$^{\circ}C/W$
Junction Temperature	$T_J$	150	$^{\circ}C$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^{\circ}C$

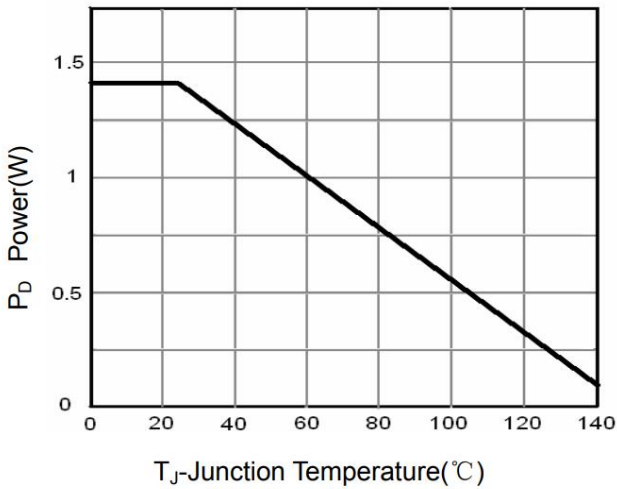
### Electrical characteristics (Ta=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 20V, V_{GS} = 0V$			1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 10V, V_{DS} = 0V$			$\pm 10$	$\mu A$
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.45		1.0	V
Drain-source on-resistance <sup>1)</sup>	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 6.5A$		19	24	m $\Omega$
		$V_{GS} = 2.5V, I_D = 5.5A$		23	30	
		$V_{GS} = 1.8V, I_D = 5A$		28	40	
Forward transconductance <sup>1)</sup>	$g_{FS}$	$V_{DS} = 5V, I_D = 6.5A$	8			S
<b>Dynamic characteristics<sup>2)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$		660		pF
Output Capacitance	$C_{oss}$			160		
Reverse Transfer Capacitance	$C_{rss}$			87		
Total Gate Charge	$Q_g$	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 6.5A$		8		nC
Gate-Source Charge	$Q_{gs}$			2.5		
Gate-Drain Charge	$Q_{gd}$			3		
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 10V, V_{GS} = 5V, R_{GEN} = 3\Omega, R_L = 1.5\Omega$		0.5		nS
Turn-on rise time	$t_r$			1		
Turn-off delay time	$t_{d(off)}$			12		
Turn-off fall time	$t_f$			4		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current <sup>1)</sup>	$I_S$				6.5	A
Diode Forward voltage	$V_{SD}$	$V_{GS} = 0V, I_S = 6.5A$			1.2	V

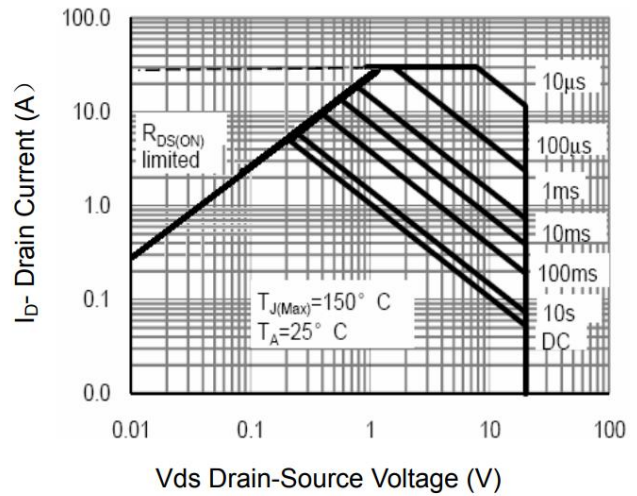
Notes:

- 1) Pulse Test: Pulse Width < 300 $\mu s$ , Duty Cycle  $\leq 2\%$ .
- 2) Guaranteed by design, not subject to production testing.

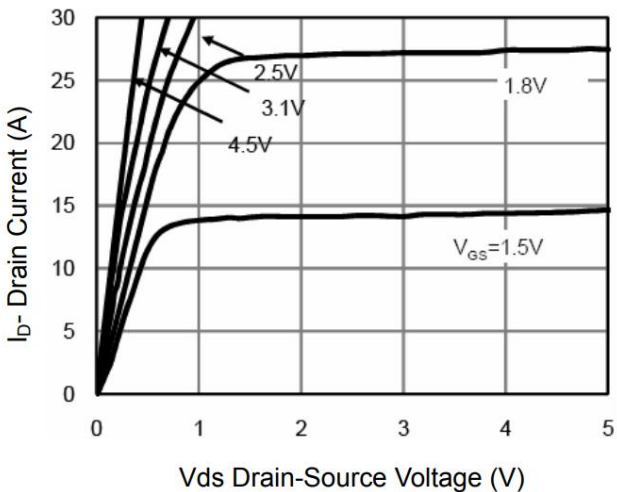
## Typical Characteristics



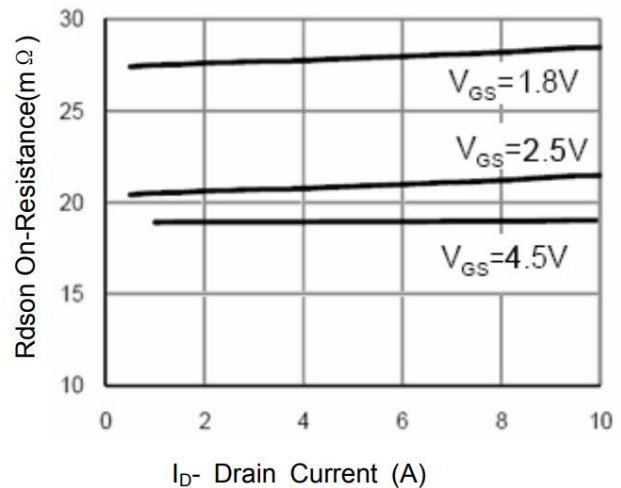
**Figure 1 Power Dissipation**



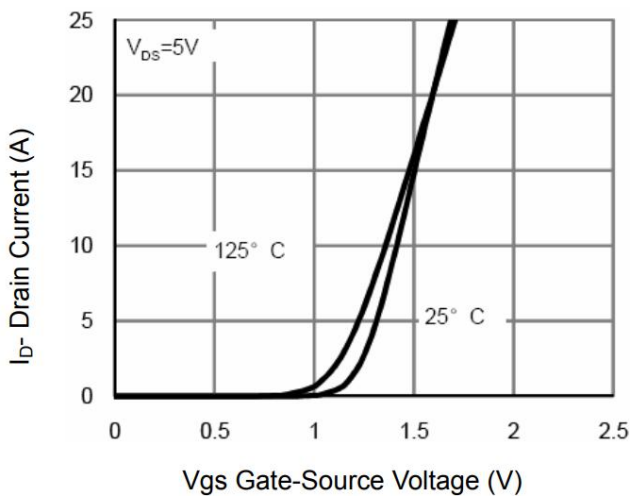
**Figure 2 Safe Operation Area**



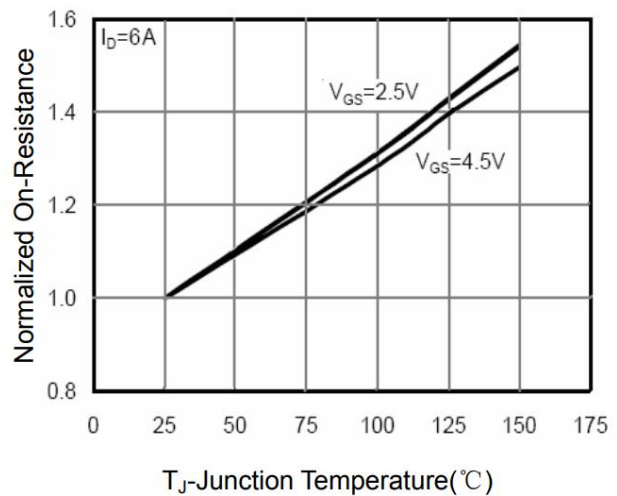
**Figure 3 Output Characteristics**



**Figure 4 Drain-Source On-Resistance**

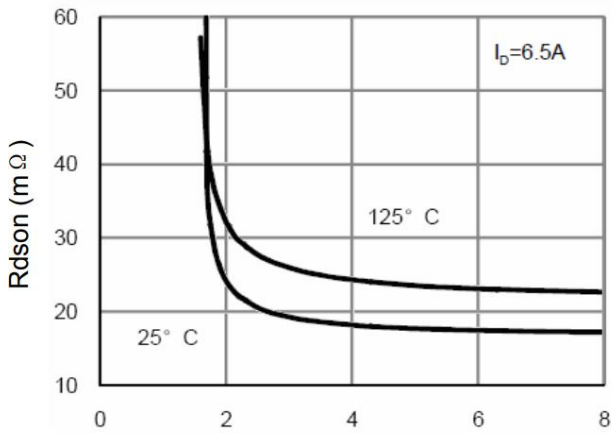


**Figure 5 Transfer Characteristics**

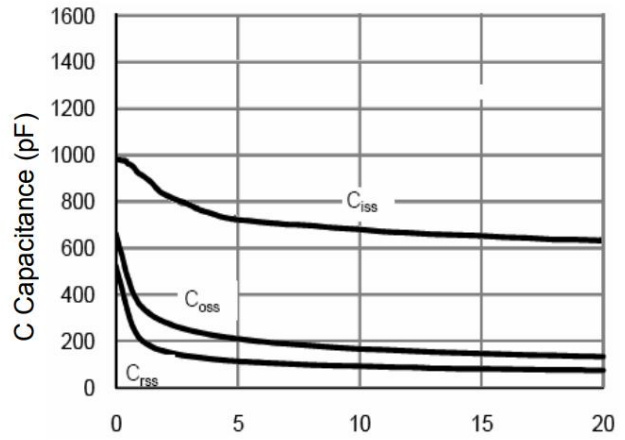


**Figure 6 Drain-Source On-Resistance**

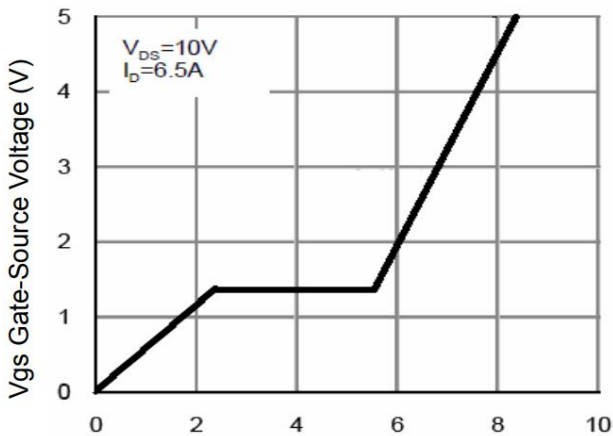
## Typical Characteristics



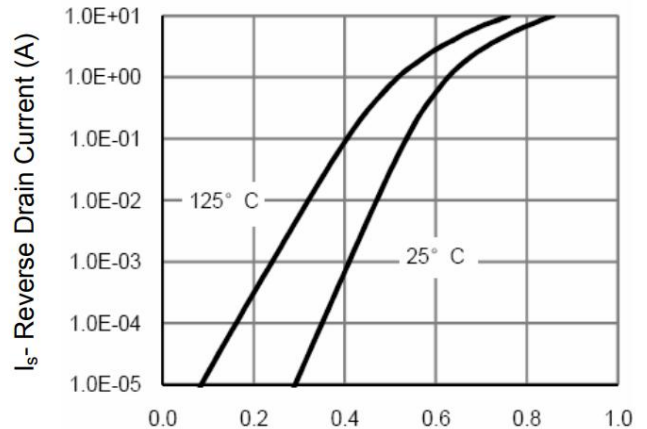
Vgs Gate-Source Voltage (V)  
**Figure 7 Rdson vs Vgs**



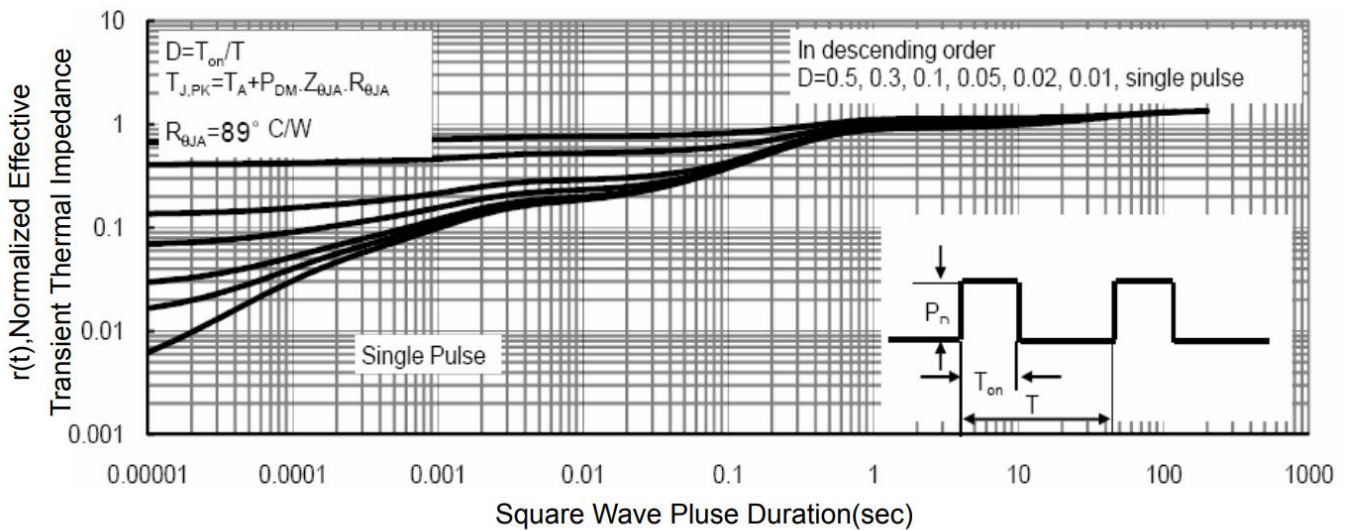
Vds Drain-Source Voltage (V)  
**Figure 8 Capacitance vs Vds**



Qg Gate Charge (nC)  
**Figure 9 Gate Charge**

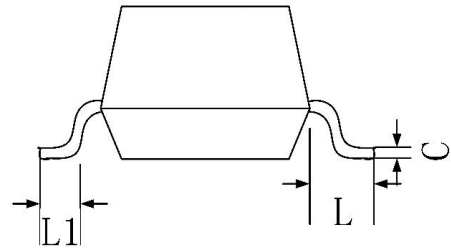
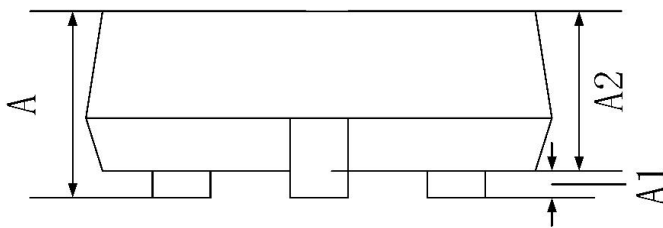
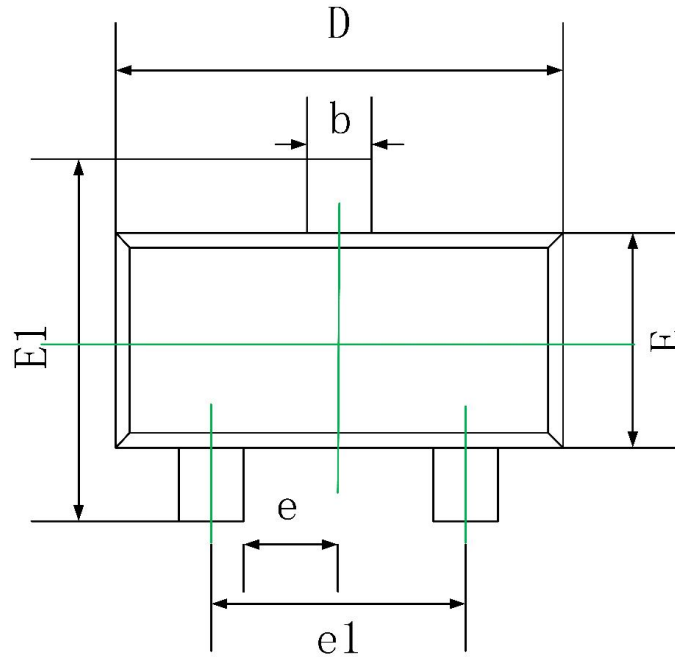


Vsd Source-Drain Voltage (V)  
**Figure 10 Source-Drain Diode Forward**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.200	0.035	0.047
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 BSC.		0.037 BSC.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020